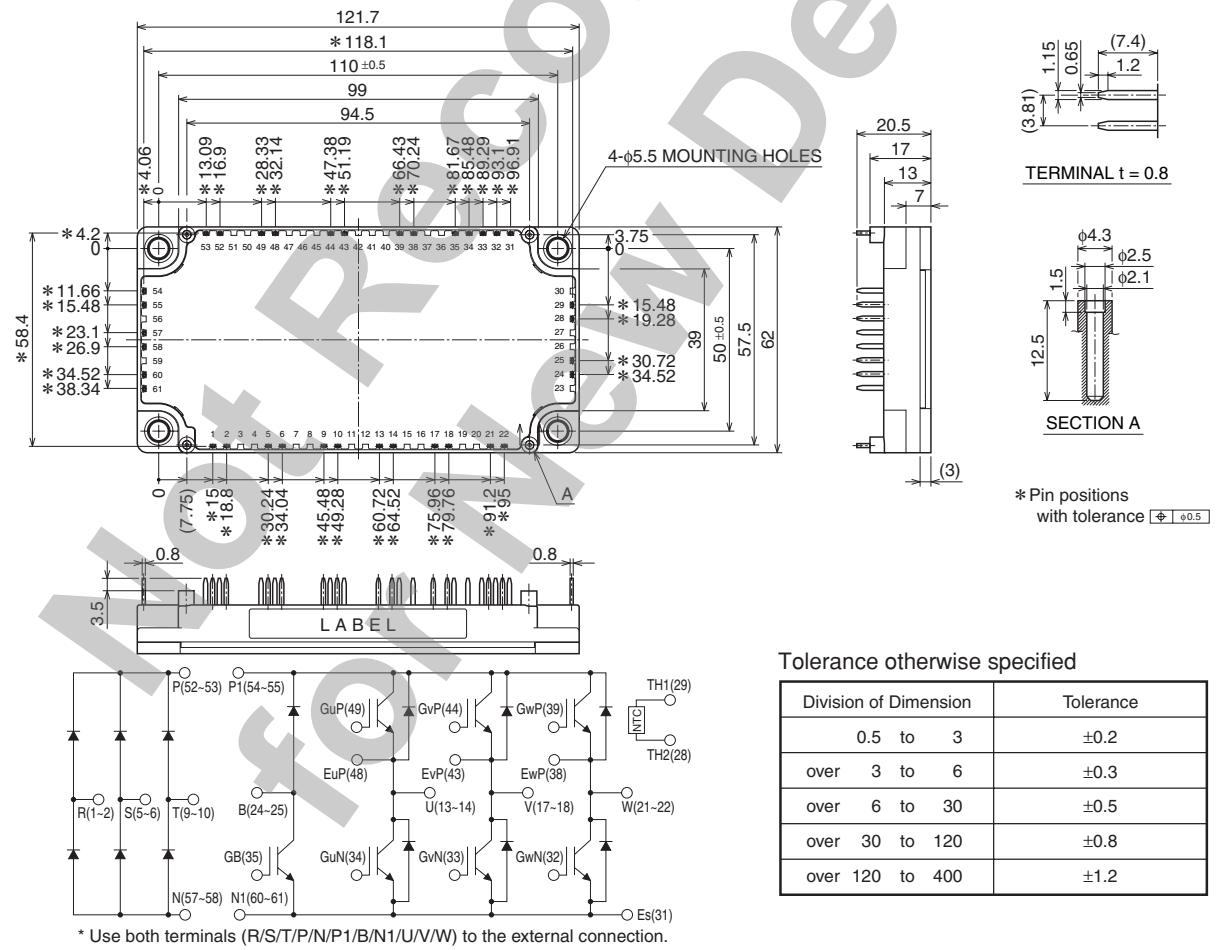


CM75MX-24A

- I_C 75A
- V_{CES} 1200V
- CIB (3-phase Converter + 3-phase Inverter + Brake)
- Flatbase Type / Insulated Package / Copper base plate
- RoHS Directive compliant

APPLICATION

General purpose Inverters, Servo Amplifiers

OUTLINE DRAWING & CIRCUIT DIAGRAM

HIGH POWER SWITCHING USE**ABSOLUTE MAXIMUM RATINGS ($T_j = 25^\circ\text{C}$, unless otherwise specified)****INVERTER PART**

Symbol	Parameter	Conditions	Rating	Unit
V _{CES}	Collector-emitter voltage	G-E Short	1200	V
V _{GES}	Gate-emitter voltage	C-E Short	±20	
I _C	Collector current	DC, $T_c = 93^\circ\text{C}$	(Note. 1)	A
I _{CRM}		Pulse	(Note. 4)	
P _{tot}	Maximum collector dissipation	$T_c = 25^\circ\text{C}$	(Note. 1, 5)	W
I _E (Note.3)	Emitter current	$T_c = 25^\circ\text{C}$	(Note. 1)	75
I _{ERM} (Note.3)	(Free wheeling diode forward current)	Pulse	(Note. 4)	150

BRAKE PART

Symbol	Parameter	Conditions	Rating	Unit
V _{CES}	Collector-emitter voltage	G-E Short	1200	V
V _{GES}	Gate-emitter voltage	C-E Short	±20	
I _C	Collector current	DC, $T_c = 97^\circ\text{C}$	(Note. 1)	A
I _{CRM}		Pulse	(Note. 4)	
P _{tot}	Maximum collector dissipation	$T_c = 25^\circ\text{C}$	(Note. 1, 5)	W
V _{RRM} (Note.3)	Repetitive peak reverse voltage		1200	V
I _F (Note.3)	Forward current	$T_c = 25^\circ\text{C}$	(Note. 1)	50
I _{FRM} (Note.3)		Pulse	(Note. 4)	100

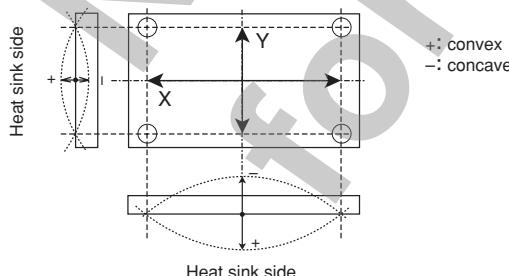
CONVERTER PART

Symbol	Parameter	Conditions	Rating	Unit
V _{RRM}	Repetitive peak reverse voltage		1600	V
E _a	Recommended AC input voltage		440	V
I _O	DC output current	3-phase full wave rectifying, $T_c = 125^\circ\text{C}$	(Note. 1)	75
I _{FSM}	Surge forward current	The sine half wave 1 cycle peak value, $f = 60\text{Hz}$, non-repetitive		750
I ² t	Current square time	Value for one cycle of surge current	2340	A ² s

MODULE

Symbol	Parameter	Conditions	Rating	Unit
T _j	Junction temperature		-40 ~ +150	°C
T _{stg}	Storage temperature		-40 ~ +125	
V _{isol}	Isolation voltage	Terminals to base plate, $f = 60\text{Hz}$, AC 1 min, RMS	2500	V
—	Base plate flatness	On the centerline X, Y (Note. 8)	±0 ~ +100	μm
—	Mounting torque	Mounting M5 screw	2.5 ~ 3.5	N·m
—	Weight	(Typical)	270	g

Note. 8: The base plate flatness measurement points are in the following figure.



ELECTRICAL CHARACTERISTICS (T_j = 25°C, unless otherwise specified)

INVERTER PART

Symbol	Parameter	Conditions	Limits			Unit
			Min.	Typ.	Max.	
ICES	Collector cut-off current	V _{CE} = V _{CES} , G-E Short	—	—	1	mA
V _{GE(th)}	Gate-emitter threshold voltage	I _C = 7.5mA, V _{CE} = 10V	6	7	8	V
IGES	Gate-emitter leakage current	V _{GE} = V _{GES} , C-E Short	—	—	0.5	µA
V _{CESat}	Collector-emitter saturation voltage	I _C = 75A, V _{GE} = 15V (Note. 6)	T _j = 25°C	—	2.0	2.6
			T _j = 125°C	—	2.2	—
		I _C = 75A, V _{GE} = 15V	Chip	—	1.9	—
C _{ies}	Input capacitance	V _{CE} = 10V, G-E Short (Note. 6)	—	—	11.5	nF
C _{oes}	Output capacitance		—	—	1.0	
C _{res}	Reverse transfer capacitance		—	—	0.23	
Q _G	Gate charge	V _{CC} = 600V, I _C = 75A, V _{GE} = 15V	—	380	—	nC
t _{d(on)}	Turn-on delay time	V _{CC} = 600V, I _C = 75A,	—	—	100	ns
t _r	Rise time	V _{GE} = ±15V, R _G = 4.3Ω,	—	—	50	
t _{d(off)}	Turn-off delay time	Inductive load	—	—	300	
t _f	Fall time		—	—	600	
t _{rr} (Note.3)	Reverse recovery time	(I _E = 75A)	—	—	200	µC
Q _{rr} (Note.3)	Reverse recovery charge		—	3.5	—	
V _{EC} (Note.3)	Emitter-collector voltage	I _E = 75A, G-E Short (Note. 6)	T _j = 25°C	—	2.6	3.4
			T _j = 125°C	—	2.16	—
		I _E = 75A, G-E Short	Chip	—	2.5	—
R _{th(j-c)Q}	Thermal resistance (Note. 1) (Junction to case)	per IGBT	—	—	0.25	K/W
R _{th(j-c)D}		per free wheeling diode	—	—	0.40	
r _g	Internal gate resistance	T _C = 25°C, per switch	—	0	—	Ω
R _G	External gate resistance		—	4.1	—	

BRAKE PART

Symbol	Parameter	Conditions	Limits			Unit
			Min.	Typ.	Max.	
ICES	Collector cut-off current	V _{CE} = V _{CES} , G-E Short	—	—	1	mA
V _{GE(th)}	Gate-emitter threshold voltage	I _C = 5mA, V _{CE} = 10V	6	7	8	V
IGES	Gate-emitter leakage current	V _{GE} = V _{GES} , C-E Short	—	—	0.5	µA
V _{CESat}	Collector-emitter saturation voltage	I _C = 50A, V _{GE} = 15V (Note. 6)	T _j = 25°C	—	2.0	2.6
			T _j = 125°C	—	2.2	—
		I _C = 50A, V _{GE} = 15V	Chip	—	1.9	—
C _{ies}	Input capacitance	V _{CE} = 10V, G-E Short (Note. 6)	—	—	8.5	nF
C _{oes}	Output capacitance		—	—	0.75	
C _{res}	Reverse transfer capacitance		—	—	0.17	
Q _G	Gate charge	V _{CC} = 600V, I _C = 50A, V _{GE} = 15V	—	250	—	nC
I _{RRM} (Note.3)	Repetitive peak reverse current	V _R = V _{RRM}	—	—	1	mA
V _F (Note.3)	Forward voltage	I _F = 50A (Note. 6)	T _j = 25°C	—	2.6	3.4
			T _j = 125°C	—	2.16	—
		I _F = 50A	Chip	—	2.5	—
R _{th(j-c)Q}	Thermal resistance (Note. 1) (Junction to case)	per IGBT	—	—	0.35	K/W
R _{th(j-c)D}		per Clamp diode	—	—	0.63	
r _g	Internal gate resistance	T _C = 25°C	—	0	—	Ω
R _G	External gate resistance		—	6.0	—	

CONVERTER PART

Symbol	Parameter	Conditions	Limits			Unit
			Min.	Typ.	Max.	
I _{RRM}	Repetitive peak reverse current	V _R = V _{RRM} , T _j = 150°C	—	—	20	mA
V _F	Forward voltage	I _F = 75A	—	1.2	1.6	V
R _{th(j-c)}	Thermal resistance (Note. 1) (Junction to case)	per Diode	—	—	0.24	K/W

HIGH POWER SWITCHING USE**NTC THERMISTOR PART**

Symbol	Parameter	Conditions	Limits			Unit
			Min.	Typ.	Max.	
R ₂₅	Zero power resistance	T _C = 25°C	4.85	5.00	5.15	kΩ
ΔR/R	Deviation of resistance	T _C = 100°C, R ₁₀₀ = 493Ω	-7.3	—	+7.8	%
B(25/50)	B constant	Approximate by equation (Note. 7)	—	3375	—	K
P ₂₅	Power dissipation	T _C = 25°C	—	—	10	mW

MODULE

Symbol	Parameter	Conditions	Limits			Unit
			Min.	Typ.	Max.	
R _{th(c-s)}	Contact thermal resistance (Case to heat sink) (Note. 1)	Thermal grease applied per 1 module (Note. 2)	—	0.015	—	K/W

Note. 1: Case temperature (T_c), heat sink temperature (T_s) measured point is just under the chips. (Refer to the figure of the chip location.)

2: Typical value is measured by using thermally conductive grease of $\lambda = 0.9\text{W}/(\text{m}\cdot\text{K})$.

3: IE, IERM, VEC, tr, Q_{rr} and E_{rr} represent ratings and characteristics of the anti-parallel, emitter-collector free wheeling diode (FWDi).

If, IFRM, VF, VRRM and IRRM represent ratings and characteristics of the Clamp diode of Brake part.

4: Pulse width and repetition rate should be such that the device junction temperature (T_j) dose not exceed T_{jmax} rating.

5: Junction temperature (T_j) should not increase beyond 150°C.

6: Pulse width and repetition rate should be such as to cause negligible temperature rise.

(Refer to the figure of the test circuit for VCEsat and VEC)

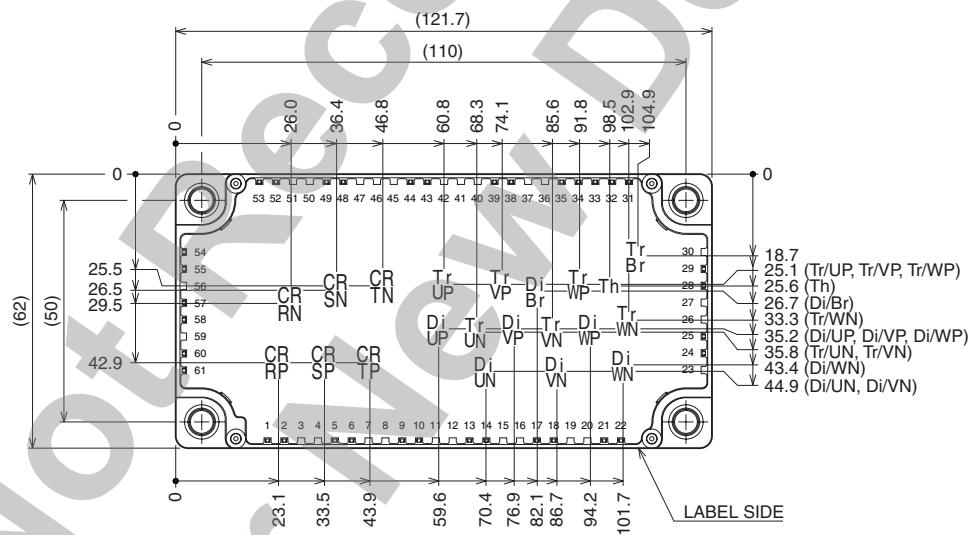
$$7: B(25/50) = \ln\left(\frac{R_{25}}{R_{50}}\right)/\left(\frac{1}{T_{25}} - \frac{1}{T_{50}}\right)$$

R₂₅: resistance at absolute temperature T₂₅ [K]; T₂₅ = 25 [°C] + 273.15 = 298.15 [K]

R₅₀: resistance at absolute temperature T₅₀ [K]; T₅₀ = 50 [°C] + 273.15 = 323.15 [K]

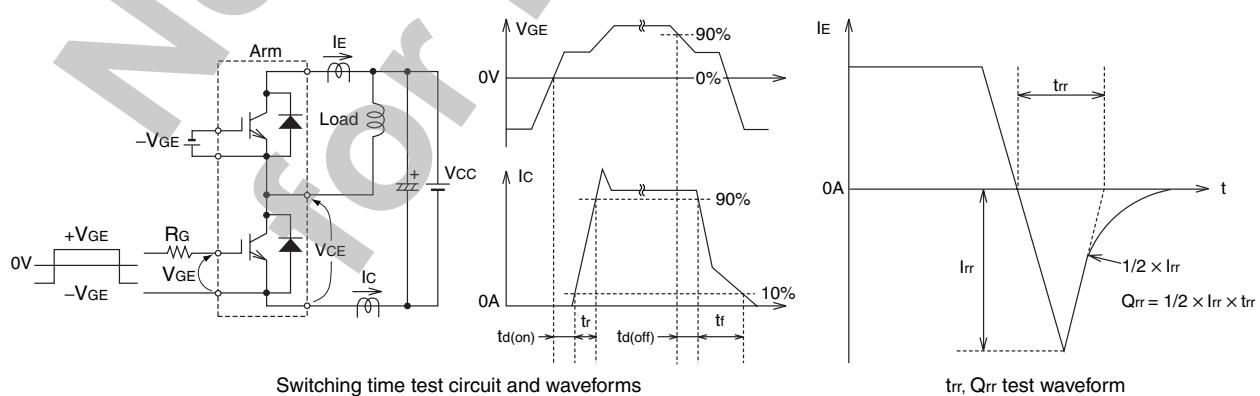
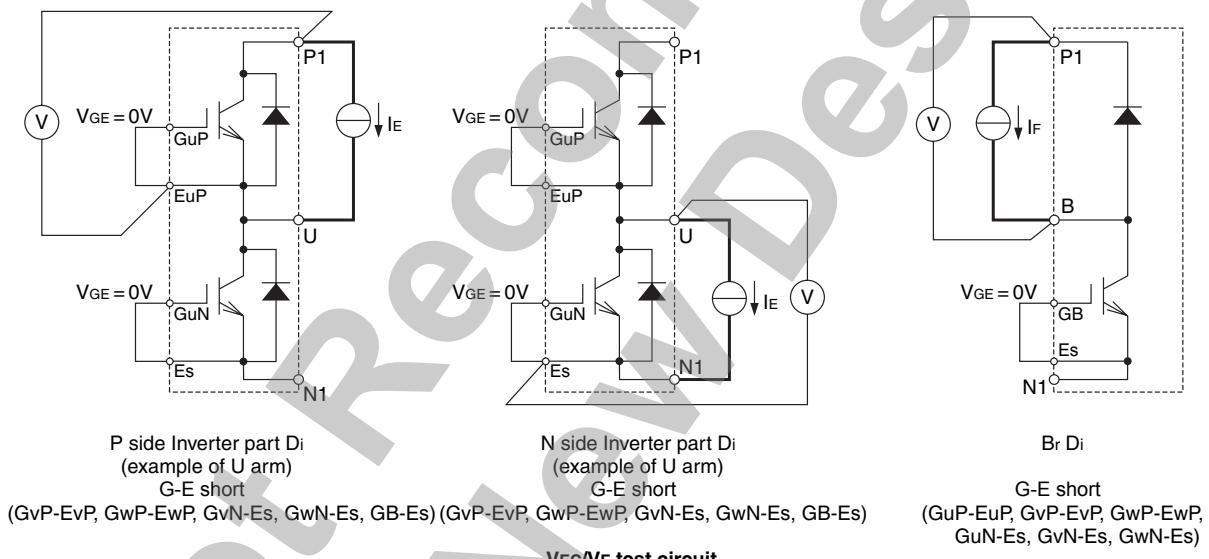
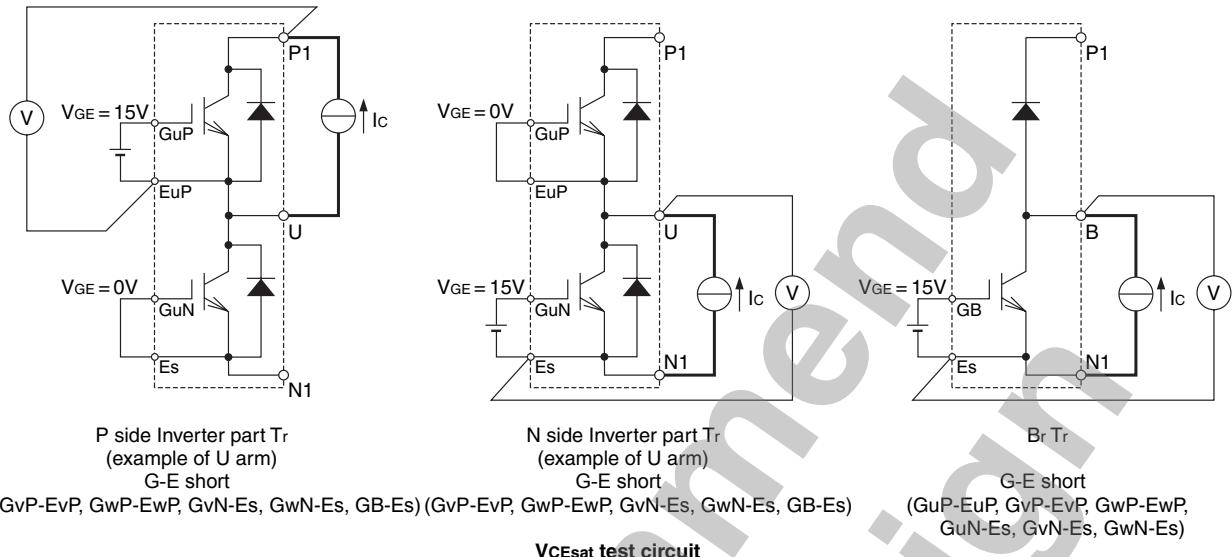
Chip Location (Top view)

Dimensions in mm (tolerance: ±1mm)



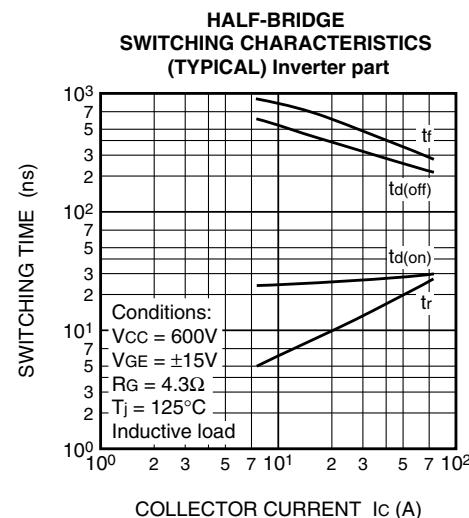
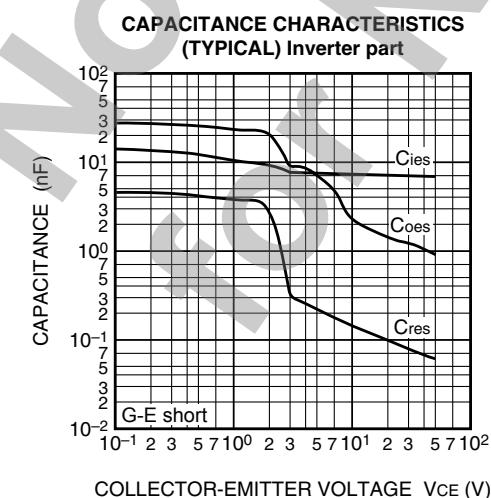
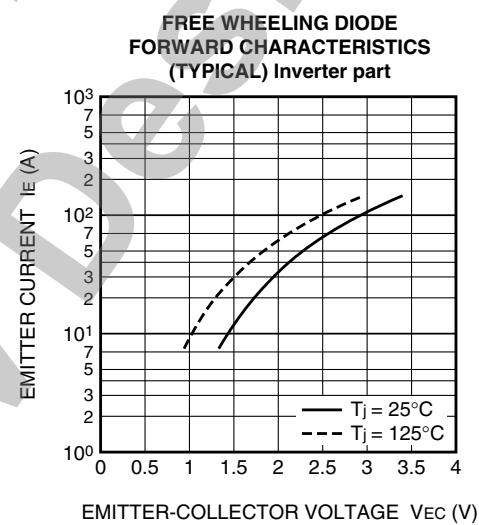
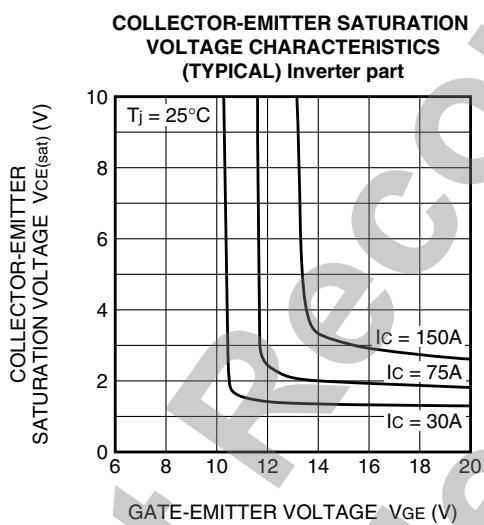
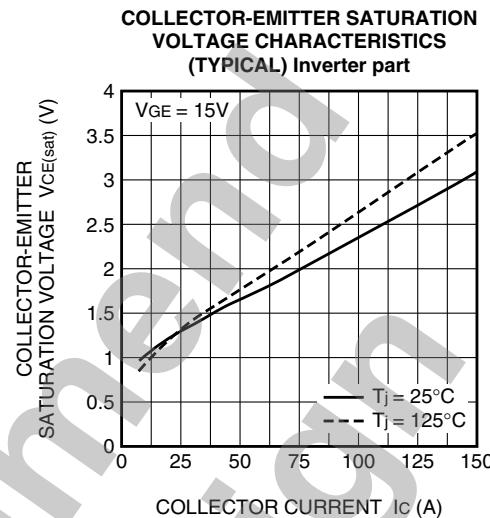
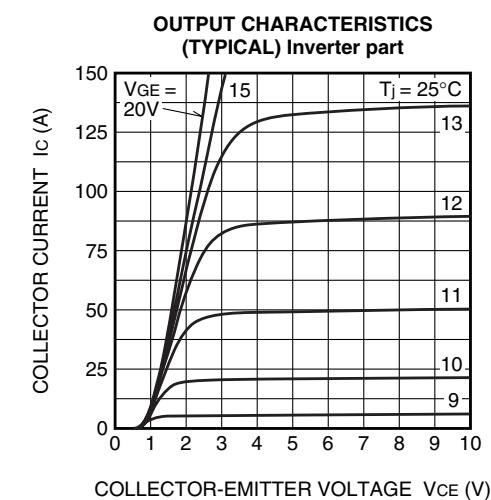
Each mark points the center position of each chip. Tr**: IGBT, Di**: FWDi (DiBr: Clamp diode), CR**: Converter diode, Th: NTC thermistor

HIGH POWER SWITCHING USE



HIGH POWER SWITCHING USE

PERFORMANCE CURVES



HIGH POWER SWITCHING USE

